APPLICA	BLE STAN	DARD							
RATING	OPERATING TEMPERATURE RANGE		-40°C TO + 85°C (NOTE 1) △ TEM		STORAGE TEMPERAT STORAGE	MPERATURE RANGE -10°C TO +		60°C (NOTE 2)	
	OPERATING HUMIDITY RANGE		40% TO + 80%	0	HUMIDITY I	RANGE	40% TO + 70% (NOTE 2))
	VOLTAGE		250V AC			VOLTAGE	30V AC		
			AWG 22 TO 26 :	2A	UL • CSA RATING		AWG 22 .	2A	
	CURRENT		AWG 28 :	1 A	IVATING	CURRENT	AWG 24 TO 28 :	1A	
			AWG 30 : 0). 5A			AWG 30 :	0. 5A	
			SPEC	IFICAT	IONS				
IT	EM		TEST METHOD			RE	QUIREMENTS	QT	АТ
CONSTR	UCTION								
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACC	ACCORDING TO DRAWING.			X
MARKING			ED VISUALLY.					Х	X
	C CHARA								
CONTACT R	ESISTANCE	100mA (DC OR 1000 Hz).			30m	30mΩ MAX.			-
INSULATION	=	500V DC.			1000	ΜΩ ΜΙΝ.		T_X	<u> </u>
RESISTANC		GEOV AC	FOR 1 min.		NO E	LACHOVED	OR BREAKDOWN.	 ^	
					INO F	LASHUVEK	ON BREAKDOWN.	X	-
	IICAL CHA								
MECHANICA OPERATION		50 TIME	S INSERTIONS AND EXTRA	ACTIONS.	1 -		SISTANCE: 30mΩ MAX.	X	
OI ERATION	l					② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			
VIBRATION			NCY 10 TO 55 Hz, SINGLE		10	① NO ELECTRICAL DISCONTINUITY OF 1μs.			
SHOCK			AT 2 h, FOR 3 DIRECTIO DURATION OF PULSE 11 n				CRACK OR LOOSENESS	X	 -
SHOCK			RECTIONS.	IIS AT 3 TIM	E3 Or	OF PARTS.			_
ENVIRO	MENTAL	CHARA	CTERISTICS						
DAMP HEAT		EXPOSE	O AT 40 ± 2 °C, 90 TO 95 °	%, 96 h.	① C	ONTACT RES	SISTANCE: 30mΩ MAX.	X	
(STEADY STATE)					3 N	② INSULATION RESISTANCE: 500MΩ MIN.③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			_
TEMPERATURE		TIME	ERATURE -55→5 TO 35→+85 →5 TO 35 °C 30→10 TO 15 →30 →10 TO15 min R 5 CYCLES.		min ② IN ③ NO	 CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 1000MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			-
COUN'	T DE		ON OF REVISIONS		ESIGNED		CHECKED To EUKIGALIMA		ATE 17.16
COUN'	T DE		DN OF REVISIONS -H-008928		ESIGNED HT. SATO	APPROVA	TS. FUKUSHIMA	14.0	7. 16
<u> </u>	T Di					APPROVE CHECKE	TS. FUKUSHIMA ED TS. SAKATA	14. C)7. 16)4. 01
_	T DI						TS. FUKUSHIMA ED TS. SAKATA ED TS. KUMAZAWA	14. 0 08. 0	07. 16 04. 01 04. 01
_	T Di					CHECKE	TS. FUKUSHIMA ED TS. SAKATA ED TS. KUMAZAWA ED KT. ISHII	14. 0 08. 0 08. 0)7. 16)4. 01
2		DIS				CHECKE DESIGNE DRAWN	TS. FUKUSHIMA ED TS. SAKATA ED TS. KUMAZAWA ED KT. ISHII VK. NAKATSU	14. 0 08. 0 08. 0 08. 0	07. 16 04. 01 04. 01 04. 01
2	ualification Tes	DIS- t AT:Assu	-H-008928	st	HT. SATO	CHECKE DESIGNE DRAWN	TS. FUKUSHIMA ED TS. SAKATA ED TS. KUMAZAWA ED KT. ISHII	14. 0 08. 0 08. 0 08. 0	07. 16 04. 01 04. 01 04. 01

SPECIFICATIONS						
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ		
RESISTANCE TO SOLDERING HEAT	1) AUTOMATIC SOLDERING (REFLOW) 《REFLOW AREA》 MAX 250°C WITHIN 10 sec. MIN 230°C WITHIN 60 sec. 《PREHEATING AREA》 150 TO 180°C 90 TO 120 sec. PUT THROUGH IN REFROW FUMACE TWICE. FEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNEVCTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290±10°C, SOLDERING TIME :3s. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	×			
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230±5°C FOR IN IMMERSION , DURATION, 3 s.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	Х	_		
DEMADIC						

REMARKS

NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT.

NOTE 2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD ,
AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM
STORAGE DURING TRANSPORTATION.

NOTE 3:THE TEMPERATURE PROFILE SHALL BE APPLIED WITHIN 168 HOURS AFTER OPENING MOISTURE-PROOF PACKAGING. WHEN 168 HOURS PASSED AFTER OPENING , APPLY THE BOTTOM REQUIREMENTS.

《REFLOW AREA》

MAX 240°C WITHIN 10 sec. MIN 230°C WITHIN 60 sec. 《PREHEATING AREA》

150 TO 180°C 90 TO 120 s.

Unless otherwise specifid , refer to IEC 60512 $oldsymbol{\Delta}$

Note QT:Qı	ualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.		ELC4-163554-05			
ß	SPECIFICATION SHEET	PART NO.	DF11C-*DP-2V(57)				
11.0	HIROSE ELECTRIC CO., LTD.	CODE NO		CL543	4	2/2	